

ALKALINE-EARTH METAL OXIDE-POLYMERIC POLISHING PAD

Abstract of the Invention

The invention provides a polishing pad useful for polishing at least one of semiconductor, magnetic and optical substrates. The polishing pad includes a polymeric matrix, the polymeric matrix having a polishing surface. In addition, polymeric microelements are distributed within the polymeric matrix and at the polishing surface of the polymeric matrix. The polymeric microelements have an outer surface and being fluid-filled for creating texture at the polishing surface. And alkaline-earth metal oxide-containing regions are distributed within each of the polymeric microelements paced to coat less than 50 percent of the outer surface of the polymeric microelements.

NO SUITABLE FIGURE